



REV.	ECN NO.	OR DESCRIPTION	REVISED	DATE
B	ECN NO.1080204		LILI	2008.12.29
C	ECN NO.S100828		ANDY	2010.08.23
D	ECN NO.S101022		ANDY	2010.10.22

- SPECIFICATIONS:**
- INSULATION RESISTANCE BETWEEN ANY ADJACENT OPEN CIRCUIT TERMINAL SHELL NOT BE LESS THAN 100M Ω MEASURED BY 500 VDC MEGGER.
 - CONTACT RESISTANCE : 50mΩ MAX.
 - INSULATION VOLTAGE WITHSTAND : 500V AC FOR ONE MINUTE.
 - UNLESS OTHERWISE SPECIFIED, TEST IS TO BE MADE AT 5-35°C IN TEMPERATURE AND 45-85% IN HUMIDITY. BUT,IF ANY VAGUE DATA IS OCCURED ON TEST RESULT, ANOTHER TEST SHALL BE MADE AT 20C±2°C IN TEMP., 60-70% IN HUMIDITY.
 - LIFE TEST : 5,000 CYCLES MIN. (NON-LOAD)
 - INSERTION FORCE : 0.4 - 3Kg.
 - WITHDRAWAL FORCE : 0.3 - 2Kg.
 - AFTER LIFE TEST, CONTACT RESISTANCE : 50mΩ MAX.
 - AFTER HUMIDITY TEST, INSULATION RESISTANCE : 50M Ω MIN.
 - PACKAGING : TAPE & REEL.
 - TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
 - HALOGEN FREE PRODUCT IDENTIFICATION MARK ON PRODUCT:
 - HALOGEN FREE PRODUCT IDENTIFICATION LOGO ON PACKING:
 - FOR LEAD-FREE PROCESS.

7	TRANSFER TERMINAL	1	PHOSPHOR BRONZE 0.2t	120u" Sn ON SOLDER GOLD FLASH ON CONTACT AREA ALL OVER 50u" Ni.
6	BREAK TERMINAL	1	PHOSPHOR BRONZE 0.2t	
5	SHUNT TERMINAL-A	1	BRASS 0.25t	
4	RING SPRING	1	PHOSPHOR BRONZE 0.2t	Ag0.5 1uM Min, ALL OVER 50u" Ni.
3	TIP SPRING	1	PHOSPHOR BRONZE 0.25t	
2	EARTH	1	COPPER ALLOY 0.3t	
1	BODY	1	HIGH TEMP.THERMOPLASTIC UL 94V-0	BLACK
UNLESS OTHERWISE SPECIFIED TOLERANCES		QTY	MATERIAL	PLATING & COLOR
DECIMALS:		TITLE		
X	:±0.5	Ø3.5 PHONE JACK		
X.X	:±0.3	PART NO. 2SJ-S351-031		
X.XX	:±0.2	SCALE:4:1 UNIT: mm		
		SHEET:1 OF 1 REV:D		
		CUSTOMER COPY		

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